

REFLOW SOLDERING

Case Size	D1	D2	D3	D4	D5
0201	0.85 (0.033)	0.30 (0.012)	0.25 (0.010)	0.30 (0.012)	0.35 (0.014)
0402	1.70 (0.067)	0.60 (0.024)	0.50 (0.020)	0.60 (0.024)	0.50 (0.020)
0603	2.30 (0.091)	0.80 (0.031)	0.70 (0.028)	0.80 (0.031)	0.75 (0.030)
0805	3.00 (0.118)	1.00 (0.039)	1.00 (0.039)	1.00 (0.039)	1.25 (0.049)
1206	4.00 (0.157)	1.00 (0.039)	2.00 (0.079)	1.00 (0.039)	1.60 (0.063)
1210	4.00 (0.157)	1.00 (0.039)	2.00 (0.079)	1.00 (0.039)	2.50 (0.098)
1808	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	2.00 (0.079)
1812	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	3.00 (0.118)
1825	5.60 (0.220)	1.00 (0.039)	3.60 (0.142)	1.00 (0.039)	6.35 (0.250)
2220	6.60 (0.260)	1.00 (0.039)	4.60 (0.181)	1.00 (0.039)	5.00 (0.197)
2225	6.60 (0.260)	1.00 (0.039)	4.60 (0.181)	1.00 (0.039)	6.35 (0.250)

Component Pad Design

Component pads should be designed to achieve good solder fillets and minimize component movement during reflow soldering. Pad designs are given below for the most common sizes of multilayer ceramic capacitors for both wave and reflow soldering. The basis of these designs is:

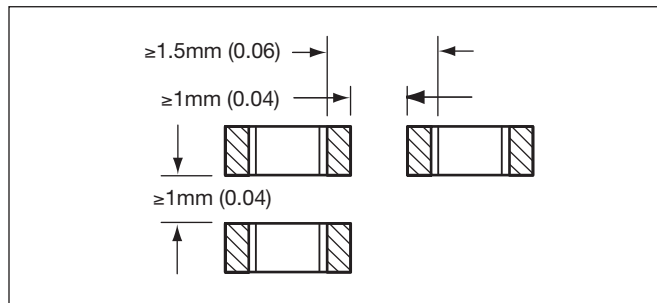
- Pad width equal to component width. It is permissible to decrease this to as low as 85% of component width but it is not advisable to go below this.
- Pad overlap 0.5mm beneath component.
- Pad extension 0.5mm beyond components for reflow and 1.0mm for wave soldering.

WAVE SOLDERING

Case Size	D1	D2	D3	D4	D5
0603	3.10 (0.12)	1.20 (0.05)	0.70 (0.03)	1.20 (0.05)	0.75 (0.03)
0805	4.00 (0.15)	1.50 (0.06)	1.00 (0.04)	1.50 (0.06)	1.25 (0.05)
1206	5.00 (0.19)	1.50 (0.06)	2.00 (0.09)	1.50 (0.06)	1.60 (0.06)

Component Spacing

For wave soldering components, must be spaced sufficiently far apart to avoid bridging or shadowing (inability of solder to penetrate properly into small spaces). This is less important for reflow soldering but sufficient space must be allowed to enable rework should it be required.



Preheat & Soldering

The rate of preheat should not exceed 4°C/second to prevent thermal shock. A better maximum figure is about 2°C/second.

For capacitors size 1206 and below, with a maximum thickness of 1.25mm, it is generally permissible to allow a temperature differential from preheat to soldering of 150°C. In all other cases this differential should not exceed 100°C.

For further specific application or process advice, please consult AVX.

Cleaning

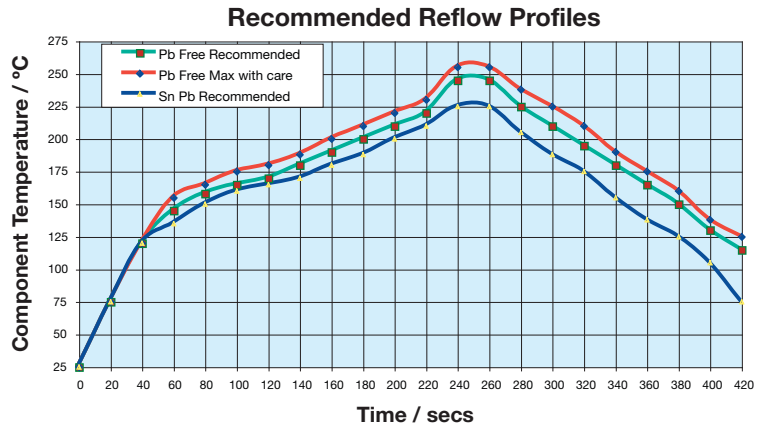
Care should be taken to ensure that the capacitors are thoroughly cleaned of flux residues especially the space beneath the capacitor. Such residues may otherwise become conductive and effectively offer a low resistance bypass to the capacitor.

Ultrasonic cleaning is permissible, the recommended conditions being 8 Watts/litre at 20-45 kHz, with a process cycle of 2 minutes vapor rinse, 2 minutes immersion in the ultrasonic solvent bath and finally 2 minutes vapor rinse.

Recommended Soldering Profiles

REFLOW SOLDER PROFILES

AVX RoHS compliant products utilize termination finishes (e.g. Sn or SnAg) that are compatible with all Pb-Free soldering systems and are fully reverse compatible with SnPb soldering systems. A recommended SnPb profile is shown for comparison; for Pb-Free soldering, IPC/JEDECJ-STD-020C may be referenced. The upper line in the chart shows the maximum envelope to which products are qualified (typically 3x reflow cycles at 260°C max). The center line gives the recommended profile for optimum wettability and soldering in Pb-Free Systems.



Preheat:

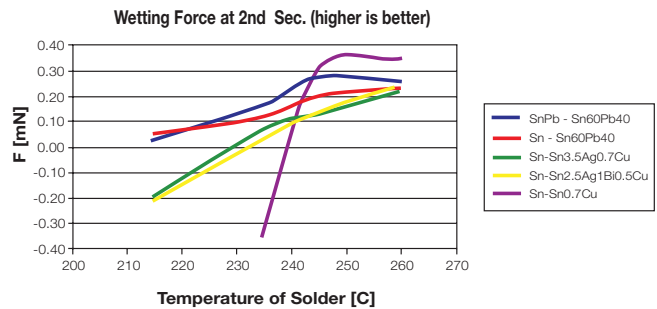
The pre-heat stabilizes the part and reduces the temperature differential prior to reflow. The initial ramp to 125°C may be rapid, but from that point (2-3)°C/sec is recommended to allow ceramic parts to heat uniformly and plastic encapsulated parts to stabilize through the glass transition temperature of the body (~ 180°C).

Reflow:

In the reflow phase, the maximum recommended time > 230°C is 40secs. Time at peak reflow is 10secs max.; optimum reflow is achieved at 250°C, (see wetting balance chart opposite) but products are qualified to 260°C max. Please reference individual product datasheets for maximum limits

Cool Down:

Cool down should not be forced and 6°C/sec is recommended. A slow cool down will result in a finer grain structure of the reflow solder in the solder fillet.



IMPORTANT NOTE: Typical Pb-Free reflow solders have a more dull and grainy appearance compared to traditional SnPb. Elevating the reflow temperature will not change this, but extending the cool down can help improve the visual appearance of the joint.

WAVE SOLDER PROFILES

For wave solder, there is no change in the recommended wave profile; all standard Pb-Free (SnCu/SnCuAg) systems operate at the same 260°C max recommended for SnPb systems.

Preheat:

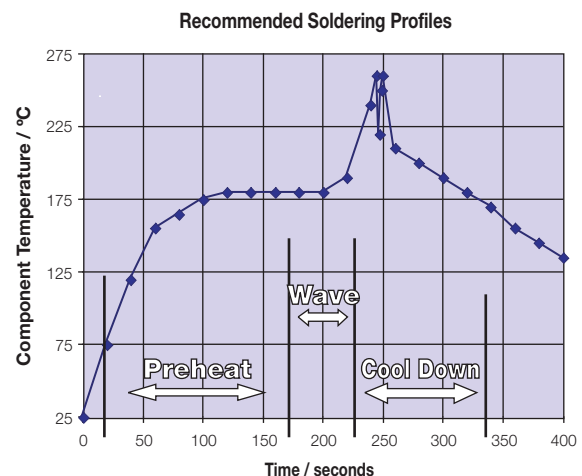
This is more important for wave solder; a higher temperature preheat will reduce the thermal shock to SMD parts that are immersed (please consult individual product data sheets for SMD parts that are suited to wave solder). SMD parts should ideally be heated from the bottom-Side prior to wave. PTH (Pin through hole) parts on the topside should not be separately heated.

Wave:

250°C – 260°C recommended for optimum solderability.

Cool Down:

As with reflow solder, cool down should not be forced and 6°C/sec is recommended. Any air knives at the end of the 2nd wave should be heated.



MLC Chip Capacitors

APPLICATION NOTES

Storage

The components should be stored in their “as received packaging” where possible. If the components are removed from their original packaging then they should be stored in an airtight container (e.g. a heat sealed plastic bag) with desiccant (e.g. silica gel). Storage area temperature should be kept between +5 degrees C and +30 degrees C with humidity < 70% RH. Storage atmosphere must be free of gas containing sulfur and chlorine. Avoid exposing the product to saline moisture or to temperature changes that might result in the formation of condensation. To assure good solderability performance we recommend that the product be used within 6 months from our shipping date, but can be used for up to 12 months. Chip capacitors may crack if exposed to hydrogen (H₂) gas while sealed or if coated with silicon, which generates hydrogen gas.

Solderability

Terminations to be well soldered after immersion in a 60/40 tin/lead solder bath at 235 ± 5°C for 2 ± 1 seconds.

Leaching

Terminations will resist leaching for at least the immersion times and conditions shown below.

Termination Type	Solder Tin/Lead/Silver	Solder Temp. °C	Immersion Time Seconds
Nickel Barrier	60/40/0	260 ± 5	30 ± 1

Lead-Free Wave Soldering

The recommended peak temperature for lead-free wave soldering is 250°C-260°C for 3-5 seconds. The other parameters of the profile remains the same as above.

The following should be noted by customers changing from lead based systems to the new lead free pastes.

- a) The visual standards used for evaluation of solder joints will need to be modified as lead free joints are not as bright as with tin-lead pastes and the fillet may not be as large.
- b) Lead-free solder pastes do not allow the same self alignment as lead containing systems. Standard mounting pads are acceptable, but machine set up may need to be modified.

General

Surface mounting chip multilayer ceramic capacitors are designed for soldering to printed circuit boards or other substrates. The construction of the components is such that they will withstand the time/temperature profiles used in both wave and reflow soldering methods.

Handling

Chip multilayer ceramic capacitors should be handled with care to avoid damage or contamination from perspiration and skin oils. The use of tweezers or vacuum pick ups

is strongly recommended for individual components. Bulk handling should ensure that abrasion and mechanical shock are minimized. Taped and reeled components provides the ideal medium for direct presentation to the placement machine. Any mechanical shock should be minimized during handling chip multilayer ceramic capacitors.

Preheat

It is important to avoid the possibility of thermal shock during soldering and carefully controlled preheat is therefore required. The rate of preheat should not exceed 4°C/second and a target figure 2°C/second is recommended. Although an 80°C to 120°C temperature differential is preferred, recent developments allow a temperature differential between the component surface and the soldering temperature of 150°C (Maximum) for capacitors of 1210 size and below with a maximum thickness of 1.25mm. The user is cautioned that the risk of thermal shock increases as chip size or temperature differential increases.

Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder to give a good joint should be used. Excessive solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. AVX terminations are suitable for all wave and reflow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Cooling

Natural cooling in air is preferred, as this minimizes stresses within the soldered joint. When forced air cooling is used, cooling rate should not exceed 4°C/second. Quenching is not recommended but if used, maximum temperature differentials should be observed according to the preheat conditions above.

Cleaning

Flux residues may be hygroscopic or acidic and must be removed. AVX MLC capacitors are acceptable for use with all of the solvents described in the specifications MIL-STD-202 and EIA-RS-198. Alcohol based solvents are acceptable and properly controlled water cleaning systems are also acceptable. Many other solvents have been proven successful, and most solvents that are acceptable to other components on circuit assemblies are equally acceptable for use with ceramic capacitors.

Circuit Board Coating

Note that when components with Sn plating on the end terminations are to be used in applications that are likely to experience conditions of high humidity under bias voltage, we strongly recommend that the circuit boards be conformally coated to protect the Sn from moisture that might lead to migration and eventual current leakage.

MLC Chip Capacitors

POST SOLDER HANDLING

Once SMP components are soldered to the board, any bending or flexure of the PCB applies stresses to the soldered joints of the components. For leaded devices, the stresses are absorbed by the compliancy of the metal leads and generally don't result in problems unless the stress is large enough to fracture the soldered connection.

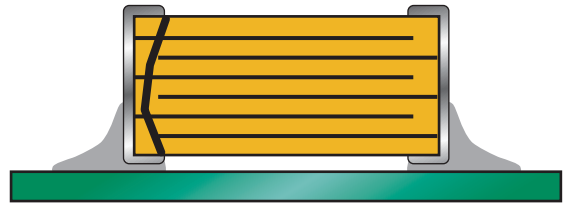
Ceramic capacitors are more susceptible to such stress because they don't have compliant leads and are brittle in nature. The most frequent failure mode is low DC resistance or short circuit. The second failure mode is significant loss of capacitance due to severing of contact between sets of the internal electrodes.

Cracks caused by mechanical flexure are very easily identified and generally take one of the following two general forms:

Mechanical cracks are often hidden underneath the termination and are difficult to see externally. However, if one end termination falls off during the removal process from PCB, this is one indication that the cause of failure was excessive mechanical stress due to board warping.



Type A:
Angled crack between bottom of device to top of solder joint.



Type B:
Fracture from top of device to bottom of device.

MLC Chip Capacitors

COMMON CAUSES OF MECHANICAL CRACKING

The most common source for mechanical stress is board depanelization equipment, such as manual breakapart, v-cutters and shear presses. Improperly aligned or dull cutters may cause torqueing of the PCB resulting in flex stresses being transmitted to components near the board edge. Another common source of flexural stress is contact during parametric testing when test points are probed. If the PCB is allowed to flex during the test cycle, nearby ceramic capacitors may be broken.

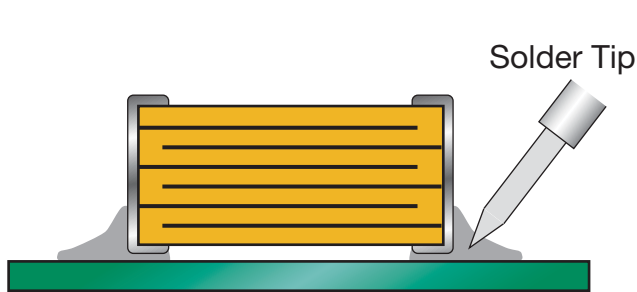
A third common source is board to board connections at vertical connectors where cables or other PCBs are connected to the PCB. If the board is not supported during the plug/unplug cycle, it may flex and cause damage to nearby components.

Special care should also be taken when handling large (>6" on a side) PCBs since they more easily flex or warp than smaller boards.

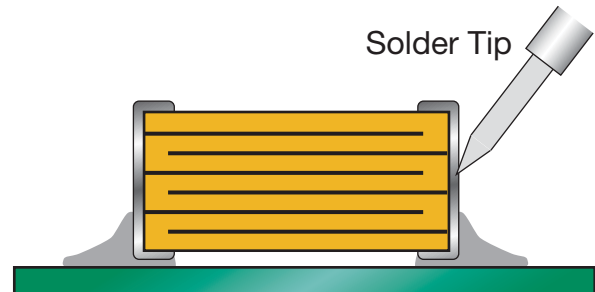
REWORKING OF MLCS

Thermal shock is common in MLCs that are manually attached or reworked with a soldering iron. *AVX strongly recommends that any reworking of MLCs be done with hot air reflow rather than soldering irons.* It is practically impossible to cause any thermal shock in ceramic capacitors when using hot air reflow.

However direct contact by the soldering iron tip often causes thermal cracks that may fail at a later date. If rework by soldering iron is absolutely necessary, it is recommended that the wattage of the iron be less than 30 watts and the tip temperature be <math><300^{\circ}\text{C}</math>. *Rework should be performed by applying the solder iron tip to the pad and not directly contacting any part of the ceramic capacitor.*



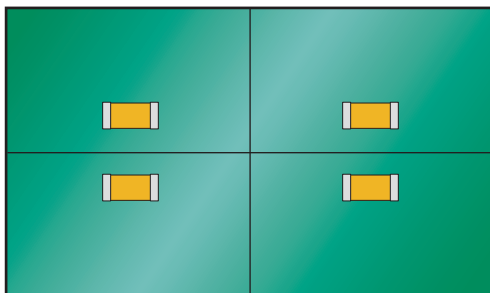
Preferred Method - No Direct Part Contact



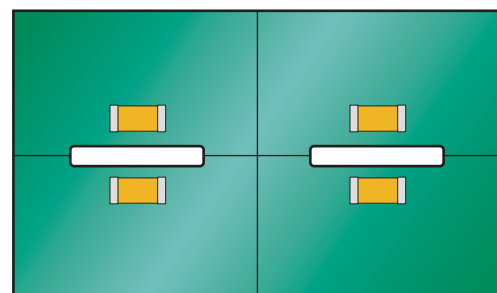
Poor Method - Direct Contact with Part

PCB BOARD DESIGN

To avoid many of the handling problems, AVX recommends that MLCs be located at least .2" away from nearest edge of board. However when this is not possible, AVX recommends that the panel be routed along the cut line, adjacent to where the MLC is located.



No Stress Relief for MLCs



Routed Cut Line Relieves Stress on MLC